



SMT power inductors

Size 8.3 x 7.5 x 5.5 (mm)

Series/Type: B82473M1

Ordering code:

Date: June 2012

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SMT power inductors

Size 8.3 x 7.5 x 5.5 (mm)

B82473M1

Rated inductance 10 ... 470 μ H
 Rated current 0.34 ... 2.3 A



Construction

Ferrite core
 Winding: enamel copper wire
 Winding soldered to terminals
 Injection molded base

Features

High mechanical stability
 Temperature range up to +150 °C
 High rated current
 Low DC resistance
 Suitable for lead-free reflow soldering
 as referenced in JEDEC J-STD 020D
 Qualification to AEC-Q200
 RoHS-compatible

Applications

Filtering of supply voltages
 Coupling, decoupling
 DC/DC converters
 Automotive electronics

Terminals

Base material CuSn6P
 Layer composition Ni, Sn (lead-free)
 Electro-plated

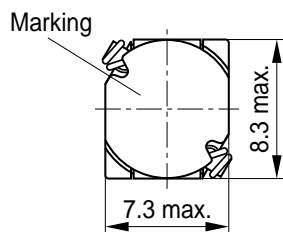
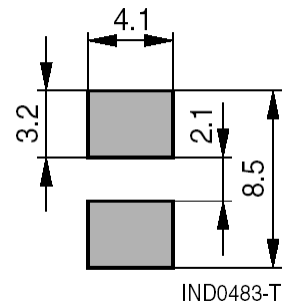
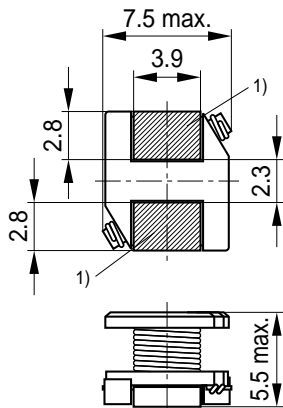
Marking

Marking on component:
 L value (μ H, coded),
 manufacturing date (YWWD)
 Minimum data on reel:
 Manufacturer, ordering code, L value,
 quantity, date of packing

Delivery mode and packing unit

16-mm blister tape, wound on 330-mm reel
 Packing unit: 1000 pcs./reel

Dimensional drawing and layout recommendation



1) Soldering area

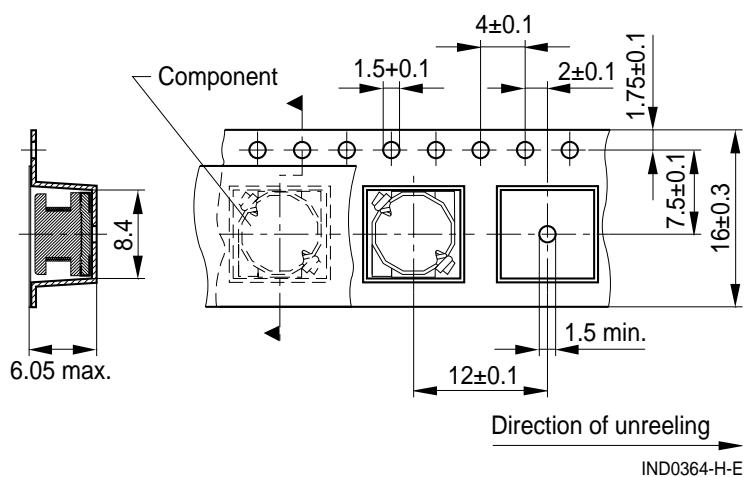
IND0482-K-E

Dimensions in mm

Component tolerances ± 0.2 mm unless otherwise noted.

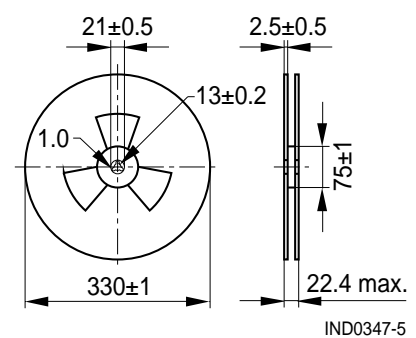
Taping and packing

Blister tape



IND0364-H-E

Reel



Dimensions in mm

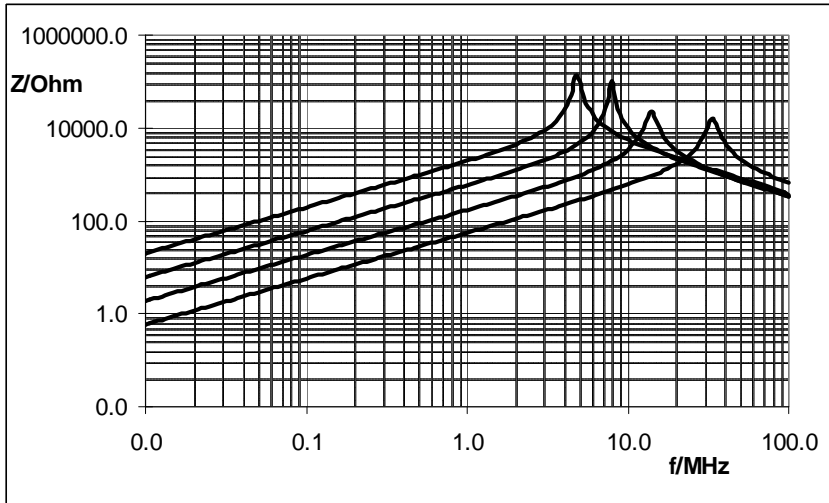
SMT power inductors
Size 8.3 x 7.5 x 5.5 (mm)
B82473M1
Technical data and measuring conditions

Rated inductance L_R	Measured with LCR meter Agilent 4284A at frequency f_L , 0.1 V, +20 °C
Rated temperature T_R	+85 °C
Rated current I_R	Max. permissible DC with temperature increase of ≤ 40 K at rated temperature
Saturation current I_{Sat}	Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%,
DC resistance R_{typ}	Measured at +20 °C
Solderability (lead-free)	Dip and look method Sn95.5Ag3.8Cu0.7: +(245 ±5) °C, (3 ±0.3) s Wetting of soldering area $\geq 90\%$ (based on IEC 60068-2-58)
Resistance to soldering heat	+260 °C, 40 s (as referenced in JEDEC J-STD 020D)
Climatic category	55/150/56 (to IEC 60068-1)
Storage conditions	Mounted: -55 °C ... +150 °C Packaged: -25 °C ... +40 °C, $\leq 75\%$ RH
Weight	Approx. 0.8 g

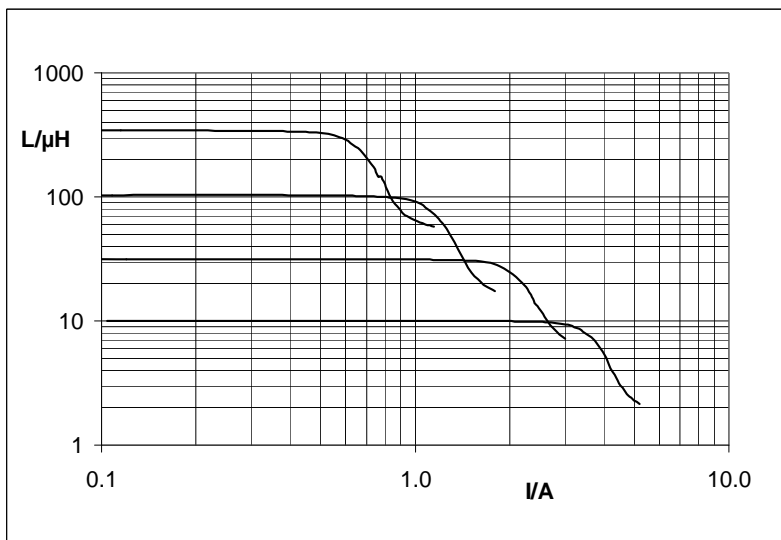
Characteristics and ordering codes

L_R μH	Tolerance	f_L MHz	I_R A	I_{sat} A	R_{max} Ω	Ordering code
10	10% = K	0.1	2.30	2.50	0.07	B82473M1103K000
15		0.1	1.80	2.00	0.09	B82473M1153K000
22		0.1	1.50	1.60	0.11	B82473M1223K000
33		0.1	1.20	1.30	0.13	B82473M1333K000
47		0.1	1.10	1.20	0.18	B82473M1473K000
68		0.1	0.85	0.90	0.28	B82473M1683K000
100		0.1	0.72	0.80	0.43	B82473M1104K000
150		0.1	0.58	0.65	0.64	B82473M1154K000
220		0.1	0.49	0.55	0.96	B82473M1224K000
330		0.1	0.40	0.45	1.26	B82473M1334K000
470		0.1	0.34	0.40	1.96	B82473M1474K000

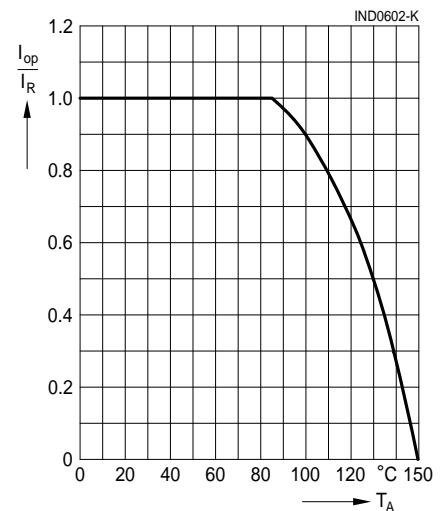
Impedance versus frequency (typical curve)



Inductance derating versus load current (typical curve)



Current derating I_{op}/I_R versus ambient temperature T_A (rated temperature $T_R = +85\text{ }^\circ\text{C}$)



Cautions and warnings

Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.

- Particular attention should be paid to the derating curves given there.
- The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.

If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation

Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

The following points must be observed if the components are potted in customer applications:

- Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
- It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
- The effect of the potting material can change the high-frequency behaviour of the components.

Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.

Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

Important notes

The following applies to all products named in this publication:

1. Some parts of this publication contain **statements about the suitability of our products for certain areas of application**. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out **that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application**. As a rule we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.
2. We also point out that **in individual cases, a malfunction of electronic components or failure before the end of their usual service life cannot be completely ruled out in the current state of the art, even if they are operated as specified**. In customer applications requiring a very high level of operational safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health (e.g. in accident prevention or life-saving systems), it must therefore be ensured by means of suitable design of the customer application or other action taken by the customer (e.g. installation of protective circuitry or redundancy) that no injury or damage is sustained by third parties in the event of malfunction or failure of an electronic component.
3. **The warnings, cautions and product-specific notes must be observed.**
4. In order to satisfy certain technical requirements, **some of the products described in this publication may contain substances subject to restrictions in certain jurisdictions (e.g. RoHS)** T t